

Material Content Data Sheet

RoHS | Halogen-Free

Sales Product Name	IPG16N10S4-61	**Issued**	02. April 2021
MA#	MA001616830		
Package	PG-TDSON-8-4	**Weight***	96.05 mg

Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip_1	inorganic material	silicon	7440-21-3	0.692	0.72	0.72	7204	7204
chip_2	inorganic material	silicon	7440-21-3	0.692	0.72	0.72	7204	7204
leadframe	inorganic material	phosphorus	7723-14-0	0.013	0.01		139	
	non noble metal	iron	7439-89-6	0.044	0.05		463	
	non noble metal	copper	7440-50-8	44.409	46.23	46.29	462360	462962
wire	non noble metal	aluminium	7429-90-5	0.729	0.76	0.76	7586	7586
encapsulation	organic material	carbon black	1333-86-4	0.092	0.10		956	
	plastics	epoxy resin	-	6.520	6.79		67880	
	inorganic material	silicondioxide	60676-86-0	39.303	40.92	47.81	409193	478029
leadfinish	non noble metal	tin	7440-31-5	1.308	1.36	1.36	13614	13614
plating	inorganic material	phosphorus	7723-14-0	0.000			1	
	non noble metal	nickel	7440-02-0	0.048	0.05	0.05	500	501
solder	non noble metal	tin	7440-31-5	0.039	0.04		407	
	noble metal	silver	7440-22-4	0.049	0.05		509	
	non noble metal	lead	7439-92-1	1.866	1.94	2.03	19430	20346
heatspreader	inorganic material	phosphorus	7723-14-0	0.000			1	
	non noble metal	iron	7439-89-6	0.000			3	
	non noble metal	copper	7440-50-8	0.245	0.26	0.26	2550	2554
*deviation	< 10%				Sum in total:	100.00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

Company	Infineon Technologies AG
Address	81726 Neubiberg
Internet	www.infineon.com